



# GaN-Based Thermoelectric Device for Micro-Power Generation

Tech ID: 21830 / UC Case 2009-389-0

## BRIEF DESCRIPTION

A novel, highly-customizable device architecture for GaN thermoelectric micro power generators.

## BACKGROUND

Currently practical thermoelectric technology consists mainly of Bi<sub>2</sub>Te<sub>3</sub> based materials. These materials however are not only toxic and scarce, but have a maximum operating temperature of roughly 150°C. The current material used for high temperature applications is SiGe, but low efficiencies and limited room for improvement necessitate the search for an improved high temperature thermoelectric material. Wide bandgap GaN and its family of alloys are promising candidates to fill this role because they are non-toxic and very stable at high temperatures.

## DESCRIPTION

Researchers at the University of California, Santa Barbara have developed a novel, highly-customizable device architecture for GaN thermoelectric micro power generators. The device structure consists of only n-type GaN with gold interconnections. Several measurements performed on this device proved the suitability of GaN at high operating temperatures for this application. For example, a maximum average temperature of 825K was achieved with no sign of device or contact degradation. This was the highest temperature tested due to limitations in the testing apparatus, not by device performance.

## ADVANTAGES

- ▶ Very stable at high temperatures (>825K)
- ▶ Low thermal conductivity
- ▶ Electrical conductivity maintained at the same level as standard nitride films

## APPLICATIONS

- ▶ Thermoelectric Devices

## CONTACT

University of California, Santa Barbara Office of Technology & Industry Alliances  
[padilla@tia.ucsb.edu](mailto:padilla@tia.ucsb.edu)  
tel: 805-893-2073.

## INVENTORS

- ▶ [DenBaars, Steven P.](#)
- ▶ [Nakamura, Shuji](#)
- ▶ [Ohta, Hiroaki](#)
- ▶ [Sztejn, Alexander](#)

## OTHER INFORMATION

### KEYWORDS

thermoelectric, energy  
  
efficiency, GaN, indaltenergy,  
  
indthermo, cenIEE, indfeat,  
  
indadvmat

### CATEGORIZED AS

- ▶ [Energy](#)
  - ▶ [Other](#)
- ▶ [Semiconductors](#)
  - ▶ [Design and Fabrication](#)

### RELATED CASES

2009-389-0

This technology is available for licensing. See below for a selection of the patents and patent applications related to this invention. Please inquire for full patent portfolio status.

PATENT STATUS

Country	Type	Number	Dated	Case
United States Of America	Issued Patent	8,692,105	04/08/2014	2009-389

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

- ▶ Lateral Growth Method for Defect Reduction of Semipolar Nitride Films
- ▶ Vertical Cavity Surface-Emitting Lasers with Continuous Wave Operation
- ▶ Eliminating Misfit Dislocations with In-Situ Compliant Substrate Formation
- ▶ III-Nitride-Based Vertical Cavity Surface Emitting Laser (VCSEL) with a Dielectric P-Side Lens
- ▶ Aluminum-cladding-free Nonpolar III-Nitride LEDs and LDs
- ▶ Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-183)
- ▶ Defect Reduction in GaN films using in-situ SiNx Nanomask
- ▶ Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
- ▶ Implantable Light Irradiation Device For Photodynamic Therapy
- ▶ Low Temperature Deposition of Magnesium Doped Nitride Films
- ▶ Transparent Mirrorless (TML) LEDs
- ▶ Improved GaN Substrates Prepared with Ammonothermal Growth
- ▶ Optimization of Laser Bar Orientation for Nonpolar Laser Diodes
- ▶ Method for Enhancing Growth of Semipolar Nitride Devices
- ▶ Ultraviolet Laser Diode on Nano-Porous AlGaIn template
- ▶ Improved Reliability & Enhanced Performance of III-Nitride Tunnel Junction Optoelectronic Devices
- ▶ Growth of Polyhedron-Shaped Gallium Nitride Bulk Crystals
- ▶ Nonpolar III-Nitride LEDs With Long Wavelength Emission
- ▶ Improved Fabrication of Nonpolar InGaIn Thin Films, Heterostructures, and Devices
- ▶ Growth of High-Quality, Thick, Non-Polar M-Plane GaN Films
- ▶ High-Efficiency, Mirrorless Non-Polar and Semi-Polar Light Emitting Devices
- ▶ Method for Growing High-Quality Group III-Nitride Crystals
- ▶ Controlled Photoelectrochemical (PEC) Etching by Modification of Local Electrochemical Potential of Semiconductor Structure
- ▶ Oxyfluoride Phosphors for Use in White Light LEDs
- ▶ Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
- ▶ (In,Ga,Al)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
- ▶ Thermally Stable, Laser-Driven White Lighting Device
- ▶ MOCVD Growth of Planar Non-Polar M-Plane Gallium Nitride
- ▶ Methods for Fabricating III-Nitride Tunnel Junction Devices
- ▶ Low-Droop LED Structure on GaN Semi-polar Substrates
- ▶ Contact Architectures for Tunnel Junction Devices
- ▶ Semi-polar LED/LD Devices on Relaxed Template with Misfit Dislocation at Hetero-interface
- ▶ Semipolar-Based Yellow, Green, Blue LEDs with Improved Performance
- ▶ III-Nitride-Based Devices Grown On Thin Template On Thermally Decomposed Material

- ▶ Growth of Semipolar III-V Nitride Films with Lower Defect Density
- ▶ III-Nitride Tunnel Junction LED with High Wall Plug Efficiency
- ▶ Tunable White Light Based on Polarization-Sensitive LEDs
- ▶ Cleaved Facet Edge-Emitting Laser Diodes Grown on Semipolar GaN
- ▶ Growth of High-Performance M-plane GaN Optical Devices
- ▶ Packaging Technique for the Fabrication of Polarized Light Emitting Diodes
- ▶ Improved Anisotropic Strain Control in Semipolar Nitride Devices
- ▶ Novel Multilayer Structure for High-Efficiency UV and Far-UV Light-Emitting Devices
- ▶ III-V Nitride Device Structures on Patterned Substrates
- ▶ Method for Increasing GaN Substrate Area in Nitride Devices
- ▶ High-Intensity Solid State White Laser Diode
- ▶ Nitride Based Ultraviolet LED with an Ultraviolet Transparent Contact
- ▶ Limiting Strain-Relaxation in III-Nitride Heterostructures by Substrate Patterning
- ▶ LED Device Structures with Minimized Light Re-Absorption
- ▶ Growth of Planar Semi-Polar Gallium Nitride
- ▶ High-Efficiency and High-Power III-Nitride Devices Grown on or Above a Strain Relaxed Template
- ▶ UV Optoelectronic Devices Based on Nonpolar and Semi-polar AlInN and AlInGaN Alloys
- ▶ Defect Reduction of Non-Polar and Semi-Polar III-Nitrides
- ▶ III-Nitride Based VCSEL with Curved Mirror on P-Side of the Aperture
- ▶ Enhancing Growth of Semipolar (Al,In,Ga,B)N Films via MOCVD

